

LPM2023 SESSION CHART (Tentative as of May 18)															
DAY-1: JUNE 13				DAY-2: JUNE 14				DAY-3: JUNE 15				DAY-4: JUNE 16			
Hirosaki Bunka Center Main Hall (1F) Opening Remark (10:00-10:10) Opening Plenary Session (10:10-12:10)				Venue will be open at 8:50.				Venue will be open at 8:50.				Venue will be open at 8:50.			
Lunch Time				ROOM 1 SESSION 9 Fundamental aspects (9:20-11:00)				ROOM 2 SESSION 10 SPECIAL SESSION 1-2 (9:40-11:00)				ROOM 3 SESSION 11 Micro-machining (9:40-11:00)			
				ROOM 4 SESSION 12 Surface processing 2 (9:20-11:00)				ROOM 1 SESSION 21 Ultra-short pulse laser processing 3 (Drilling, Cutting) (9:20-11:00)				ROOM 2 SESSION 22 SPECIAL SESSION 1-4 (9:20-11:00)			
Lunch Time				ROOM 3 SESSION 23 Glass/ Ceramic processing (9:20-11:00)				ROOM 4 SESSION 24 LIPSS, micro-patterning and structuring 1 (9:20-11:00)				ROOM 1 SESSION 33 Ultra-short pulse laser processing 6 (Metal) (9:20-10:40)			
				ROOM 2 SESSION 34 Laser, optics and systems for laser micro-processing 1 (9:10-10:40)				ROOM 3 SESSION 35 SPECIAL SESSION 2-3 (9:10-10:40)				ROOM 4 SESSION 36 Process monitoring and control 1 (9:40-10:40)			
Lunch Time				COFFEE BREAK				COFFEE BREAK				COFFEE BREAK			
				ROOM 1 SESSION 37 Ultra-short pulse laser processing 7 (New trend) (11:00-12:20)				ROOM 2 SESSION 38 Lasers, optics and systems for laser micro-processing 2 (11:00-12:00)				ROOM 3 SESSION 39 SPECIAL SESSION 2-4 (11:00-12:20)			
Lunch Time				ROOM 4 SESSION 40 Process monitoring and control 2 (11:00-12:20)				ROOM 1 SESSION 25 Ultra-short pulse laser processing 4 (3D glass modificationand microfluidic chip) (14:10-15:50)				ROOM 2 SESSION 26 SPECIAL SESSION 1-5 (14:10-16:00)			
				ROOM 3 SESSION 27 SPECIAL SESSION 2-1 Machine Learning and Simulation for Laser Processing (14:10-16:05)				ROOM 4 SESSION 28 LIPSS, micro-patterning and structuring 2 (14:10-15:50)				ROOM 1 SESSION 29 Ultra-short pulse laser processing 5 (3D Micro/Nano fabrication of transparent materials) (16:30-17:50)			
Lunch Time				ROOM 2 SESSION 30 Laser-based direct-write techniques 2 (16:30-18:00)				ROOM 3 SESSION 31 SPECIAL SESSION 2-2 (16:30-18:00)				ROOM 4 SESSION 32 LIPSS, micro-patterning and structuring 3 (16:30-18:00)			
				ROOM 1 SESSION 5 Burst ablation (16:30-17:50)				ROOM 2 SESSION 6 SPECIAL SESSION 1-6 (16:30-17:50)				ROOM 3 SESSION 7 3D Micro/Nano fabrication 2 (16:30-18:10)			
Lunch Time				ROOM 4 SESSION 8 Surface processing 1 (16:30-18:10)				ROOM 1 SESSION 17 Ultra-short pulse laser processing 2 (Surface of transparent materials) (16:30-18:10)				ROOM 2 SESSION 18 Laser-based direct-write techniques 1 (16:30-18:10)			
				ROOM 3 SESSION 19 Cutting and other processing technologies (16:30-18:10)				ROOM 4 SESSION 20 Micro-patterning structuring and modification (16:30-18:10)				ROOM 1 SESSION 21 Ultra-short pulse laser processing 3 (Drilling, Cutting) (9:20-11:00)			
Lunch Time				ROOM 2 SESSION 22 SPECIAL SESSION 1-4 (9:20-11:00)				ROOM 3 SESSION 23 Glass/ Ceramic processing (9:20-11:00)				ROOM 4 SESSION 24 LIPSS, micro-patterning and structuring 1 (9:20-11:00)			
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